

SOT662-1

plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 5 x 5 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN20
Package type industry code	HVQFN20
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-10-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.9	-	5	5.1	mm
E	package width		4.9	-	5	5.1	mm
A	seated height		[tbd]	-	0.85	1	mm
A ₂	package height		[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination		-	-	20	-	



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2. Package outline

HVQFN20: plastic thermal enhanced very thin quad flat package; no leads;
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SOT662-1

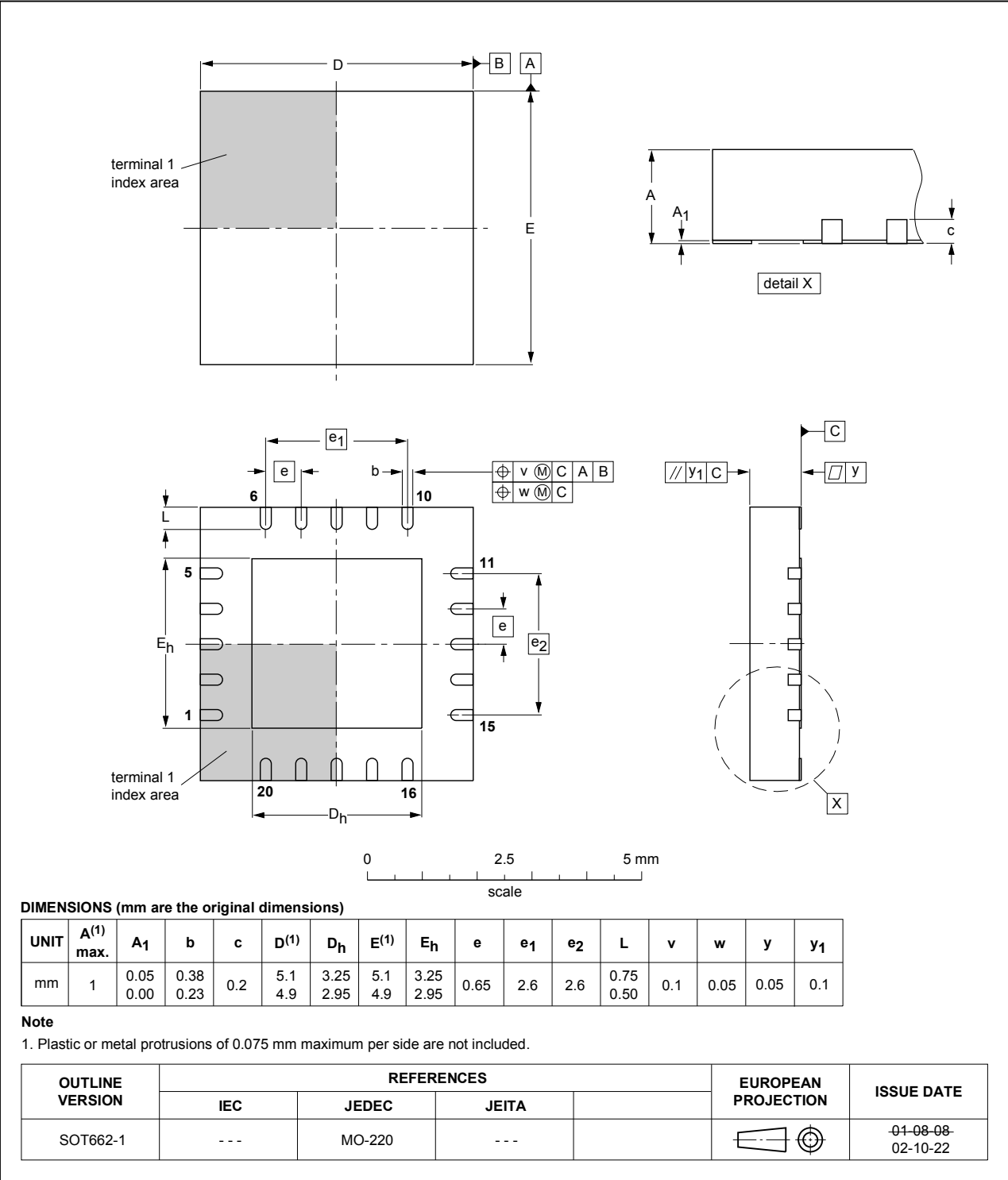


Fig. 1. Package outline HVQFN20 (SOT662-1)

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3. Soldering

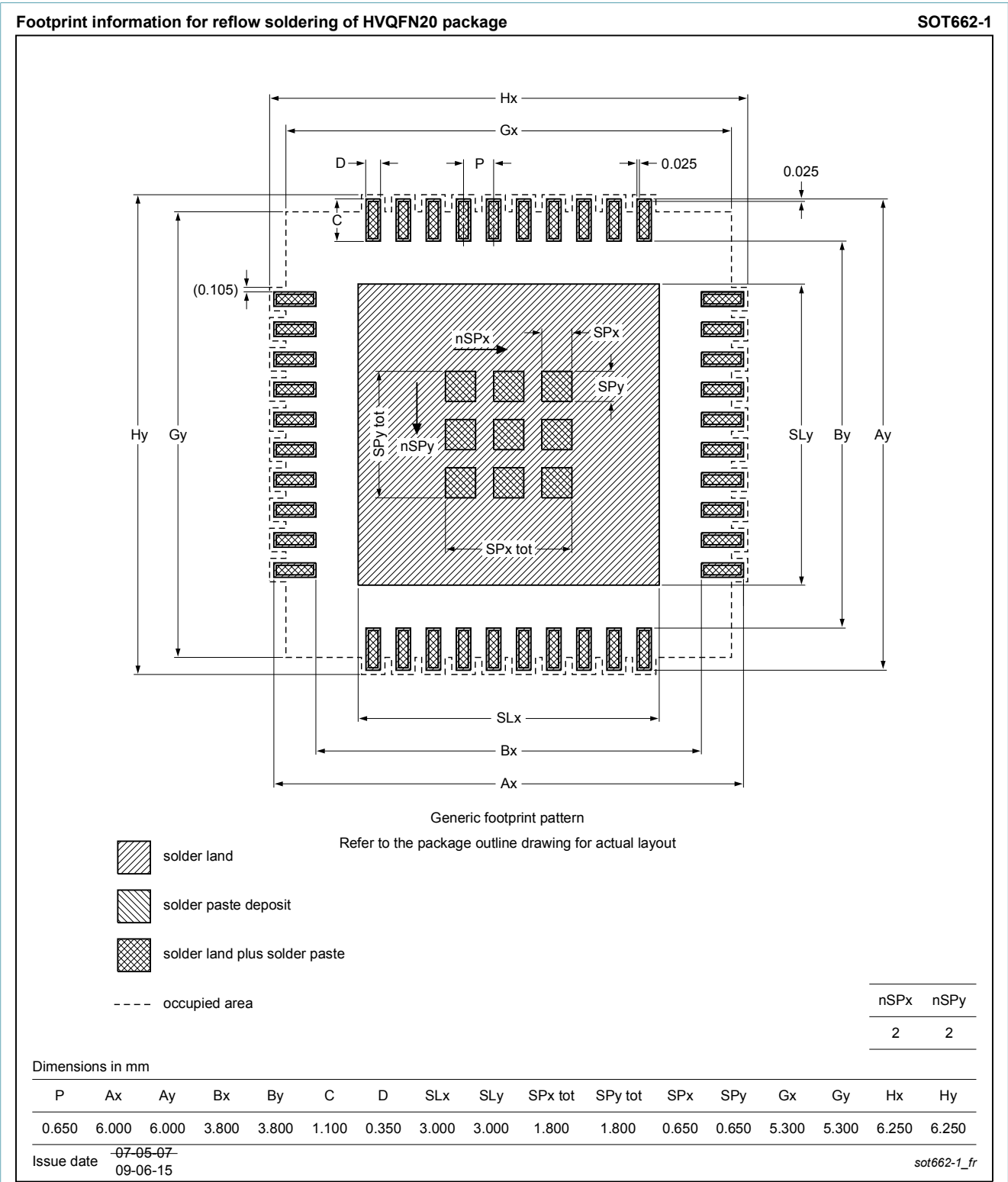


Fig. 2. Reflow soldering footprint for HVQFN20 (SOT662-1)

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4. Legal information

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